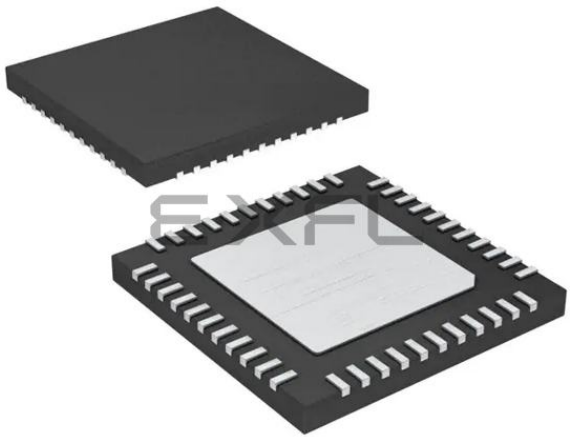
Microchip Technology - DSPIC33FJ64GP204T-I/ML Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DCI, DMA, I²S, POR, PWM, WDT
Number of I/O	35
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 13x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj64gp204t-i-ml

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Type	Buffer Type	PPS	Description
SCL1	I/O	ST	No	Synchronous serial clock input/output for I2C1.
SDA1	I/O	ST	No	Synchronous serial data input/output for I2C1.
ASCL1	I/O	ST	No	Alternate synchronous serial clock input/output for I2C1.
ASDA1	I/O	ST	No	Alternate synchronous serial data input/output for I2C1.
TMS	I	ST	No	JTAG Test mode select pin.
TCK	I	ST	No	JTAG test clock input pin.
TDI	I	ST	No	JTAG test data input pin.
TDO	O	—	No	JTAG test data output pin.
C1RX	I	ST	Yes	ECAN1 bus receive pin.
C1TX	O	—	Yes	ECAN1 bus transmit pin.
RTCC	O	—	No	Real-Time Clock Alarm Output.
CVREF	O	ANA	No	Comparator Voltage Reference Output.
C1IN-	I	ANA	No	Comparator 1 Negative Input.
C1IN+	I	ANA	No	Comparator 1 Positive Input.
C1OUT	O	—	Yes	Comparator 1 Output.
C2IN-	I	ANA	No	Comparator 2 Negative Input.
C2IN+	I	ANA	No	Comparator 2 Positive Input.
C2OUT	O	—	Yes	Comparator 2 Output.
PMA0	I/O	TTL/ST	No	Parallel Master Port Address Bit 0 Input (Buffered Slave modes) and Output (Master modes).
PMA1	I/O	TTL/ST	No	Parallel Master Port Address Bit 1 Input (Buffered Slave modes) and Output (Master modes).
PMA2 -PMPA10	O	—	No	Parallel Master Port Address (Demultiplexed Master Modes).
PMBE	O	—	No	Parallel Master Port Byte Enable Strobe.
PMCS1	O	—	No	Parallel Master Port Chip Select 1 Strobe.
PMD0-PMPD7	I/O	TTL/ST	No	Parallel Master Port Data (Demultiplexed Master mode) or Address/ Data (Multiplexed Master modes).
PMRD	O	—	No	Parallel Master Port Read Strobe.
PMWR	O	—	No	Parallel Master Port Write Strobe.
DAC1RN	O	—	No	DAC1 Right Channel Negative Output.
DAC1RP	O	—	No	DAC1 Right Channel Positive Output.
DAC1RM	O	—	No	DAC1 Right Channel Middle Point Value (typically 1.65V).
DAC1LN	O	—	No	DAC1 Left Channel Negative Output.
DAC1LP	O	—	No	DAC1 Left Channel Positive Output.
DAC1LM	O	—	No	DAC1 Left Channel Middle Point Value (typically 1.65V).
COFS	I/O	ST	Yes	Data Converter Interface frame synchronization pin.
CSCK	I/O	ST	Yes	Data Converter Interface serial clock input/output pin.
CSDI	I	ST	Yes	Data Converter Interface serial data input pin
CSDO	O	—	Yes	Data Converter Interface serial data output pin.
PGED1	I/O	ST	No	Data I/O pin for programming/debugging communication channel 1.
PGEC1	I	ST	No	Clock input pin for programming/debugging communication channel 1.
PGED2	I/O	ST	No	Data I/O pin for programming/debugging communication channel 2.
PGEC2	I	ST	No	Clock input pin for programming/debugging communication channel 2.
PGED3	I/O	ST	No	Data I/O pin for programming/debugging communication channel 3.
PGEC3	I	ST	No	Clock input pin for programming/debugging communication channel 3.
$\overline{MCLR}$	I/P	ST	No	Master Clear (Reset) input. This pin is an active-low Reset to the device.
AVDD	P	P	No	Positive supply for analog modules. This pin must be connected at all times.

Legend: CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels
TTL = TTL input buffer
Analog = Analog input
O = Output
PPS = Peripheral Pin Select
P = Power
I = Input

TABLE 4-21: PERIPHERAL PIN SELECT INPUT REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPINR0	0680	—	—	—	INT1R<4:0>					—	—	—	—	—	—	—	—	1F00
RPINR1	0682	—	—	—	—	—	—	—	—	—	—	—	INT2R<4:0>					001F
RPINR3	0686	—	—	—	T3CKR<4:0>					—	—	—	T2CKR<4:0>					1F1F
RPINR4	0688	—	—	—	T5CKR<4:0>					—	—	—	T4CKR<4:0>					1F1F
RPINR7	068E	—	—	—	IC2R<4:0>					—	—	—	IC1R<4:0>					1F1F
RPINR10	0694	—	—	—	IC8R<4:0>					—	—	—	IC7R<4:0>					1F1F
RPINR11	0696	—	—	—	—	—	—	—	—	—	—	—	OCFAR<4:0>					001F
RPINR18	06A4	—	—	—	U1CTSR<4:0>					—	—	—	U1RXR<4:0>					1F1F
RPINR19	06A6	—	—	—	U2CTSR<4:0>					—	—	—	U2RXR<4:0>					1F1F
RPINR20	06A8	—	—	—	SCK1R<4:0>					—	—	—	SDI1R<4:0>					1F1F
RPINR21	06AA	—	—	—	—	—	—	—	—	—	—	—	SS1R<4:0>					001F
RPINR22	06AC	—	—	—	SCK2R<4:0>					—	—	—	SDI2R<4:0>					1F1F
RPINR23	06AE	—	—	—	—	—	—	—	—	—	—	—	SS2R<4:0>					001F
RPINR24	06B0	—	—	—	CSCKR<4:0>					—	—	—	CSDIR<4:0>					1F1F
RPINR25	06B2	—	—	—	—	—	—	—	—	—	—	—	COFSR<4:0>					001F
RPINR26(1)	06B4	—	—	—	—	—	—	—	—	—	—	—	C1RXR<4:0>					001F

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register is present only for dsPIC33FJ128GP802/804 and dsPIC33FJ64GP802/804

5.2 RTSP Operation

The dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 Flash program memory array is organized into rows of 64 instructions or 192 bytes. RTSP allows the user application to erase a page of memory, which consists of eight rows (512 instructions) at a time, and to program one row or one word at a time. Table 30-12 shows typical erase and programming times. The 8-row erase pages and single row write rows are edge-aligned from the beginning of program memory, on boundaries of 1536 bytes and 192 bytes, respectively.

The program memory implements holding buffers that can contain 64 instructions of programming data. Prior to the actual programming operation, the write data must be loaded into the buffers sequentially. The instruction words loaded must always be from a group of 64 boundary.

The basic sequence for RTSP programming is to set up a Table Pointer, then do a series of `TBLWT` instructions to load the buffers. Programming is performed by setting the control bits in the NVMCON register. A total of 64 `TBLWTL` and `TBLWTH` instructions are required to load the instructions.

All of the table write operations are single-word writes (two instruction cycles) because only the buffers are written. A programming cycle is required for programming each row.

5.3 Programming Operations

A complete programming sequence is necessary for programming or erasing the internal Flash in RTSP mode. The processor stalls (waits) until the programming operation is finished.

The programming time depends on the FRC accuracy (see Table 30-19) and the value of the FRC Oscillator Tuning register (see Register 9-4). Use the formula in Equation 5-1 to calculate the minimum and maximum values for the Row Write Time, Page Erase Time and Word Write Cycle Time parameters (see Table 30-12).

EQUATION 5-1: PROGRAMMING TIME

$$\frac{T}{7.37\ MHz \times (FRC\ Accuracy)\% \times (FRC\ Tuning)\%}$$

For example, if the device is operating at +125°C, the FRC accuracy will be ±5%. If the TUN<5:0> bits (see Register 9-4) are set to `'b111111`, the minimum row write time is equal to Equation 5-2.

EQUATION 5-2: MINIMUM ROW WRITE TIME

$$T_{RW} = \frac{11064\ Cycles}{7.37\ MHz \times (1 + 0.05) \times (1 - 0.00375)} = 1.435ms$$

The maximum row write time is equal to Equation 5-3.

EQUATION 5-3: MAXIMUM ROW WRITE TIME

$$T_{RW} = \frac{11064\ Cycles}{7.37\ MHz \times (1 - 0.05) \times (1 - 0.00375)} = 1.586ms$$

Setting the WR bit (NVMCON<15>) starts the operation, and the WR bit is automatically cleared when the operation is finished.

5.4 Control Registers

Two SFRs are used to read and write the program Flash memory: NVMCON and NVMKEY.

The NVMCON register (Register 5-1) controls which blocks are to be erased, which memory type is to be programmed and the start of the programming cycle.

NVMKEY (Register 5-2) is a write-only register that is used for write protection. To start a programming or erase sequence, the user application must consecutively write 0x55 and 0xAA to the NVMKEY register. Refer to **Section 5.3 "Programming Operations"** for further details.

5.5 Flash Resources

Many useful resources related to Flash memory are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser:
http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en532311

5.5.1 KEY RESOURCES

- **Section 5. "Flash Programming"** (DS70191)
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related dsPIC33F/PIC24H Family Reference Manuals Sections
- Development Tools

9.1 CPU Clocking System

The dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 devices provide seven system clock options:

- Fast RC (FRC) Oscillator
- FRC Oscillator with Phase-Locked Loop (PLL)
- Primary (XT, HS or EC) Oscillator
- Primary Oscillator with PLL
- Secondary (LP) Oscillator
- Low-Power RC (LPRC) Oscillator
- FRC Oscillator with postscaler

9.1.1 SYSTEM CLOCK SOURCES

The Fast RC (FRC) internal oscillator runs at a nominal frequency of 7.37 MHz. User software can tune the FRC frequency. User software can optionally specify a factor (ranging from 1:2 to 1:256) by which the FRC clock frequency is divided. This factor is selected using the FRCDIV<2:0> bits (CLKDIV<10:8>).

The primary oscillator can use one of the following as its clock source:

- Crystal (XT): Crystals and ceramic resonators in the range of 3 MHz to 10 MHz. The crystal is connected to the OSC1 and OSC2 pins.
- High-Speed Crystal (HS): Crystals in the range of 10 MHz to 40 MHz. The crystal is connected to the OSC1 and OSC2 pins.
- External Clock (EC): External clock signal is directly applied to the OSC1 pin.

The secondary (LP) oscillator is designed for low power and uses a 32.768 kHz crystal or ceramic resonator. The LP oscillator uses the SOSCI and SOSCO pins.

The Low-Power RC (LPRC) internal oscIllator runs at a nominal frequency of 32.768 kHz. It is also used as a reference clock by the Watchdog Timer (WDT) and Fail-Safe Clock Monitor (FSCM).

The clock signals generated by the FRC and primary oscillators can be optionally applied to an on-chip PLL to provide a wide range of output frequencies for device operation. PLL configuration is described in **Section 9.1.4 "PLL Configuration"**.

The FRC frequency depends on the FRC accuracy (see Table 30-19) and the value of the FRC Oscillator Tuning register (see Register 9-4).

9.1.2 SYSTEM CLOCK SELECTION

The oscillator source used at a device Power-on Reset event is selected using Configuration bit settings. The oscillator Configuration bit settings are located in the Configuration registers in the program memory. (Refer to **Section 27.1 "Configuration Bits"** for further details.) The Initial Oscillator Selection Configuration bits, FNOSC<2:0> (FOSCSEL<2:0>), and the Primary Oscillator Mode Select Configuration bits, POSCMD<1:0> (FOSC<1:0>), select the oscillator source that is used at a Power-on Reset. The FRC primary oscillator is the default (unprogrammed) selection.

The Configuration bits allow users to choose among 12 different clock modes, shown in Table 9-1.

The output of the oscillator (or the output of the PLL if a PLL mode has been selected) FOSC is divided by 2 to generate the device instruction clock (FCY) and peripheral clock time base (FP). FCY defines the operating speed of the device, and speeds up to 40 MHz are supported by the dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 architecture.

Instruction execution speed or device operating frequency, FCY, is given by:

EQUATION 9-1: DEVICE OPERATING FREQUENCY

$$FCY = \frac{FOSC}{2}$$

9.1.3 AUXILIARY OSCILLATOR

The Auxiliary Oscillator (AOSC) can be used for peripherals that need to operate at a frequency unrelated to the system clock such as a Digital-to-Analog Converter (DAC).

The Auxiliary Oscillator can use one of the following as its clock source:

- Crystal (XT): Crystal and ceramic resonators in the range of 3 MHz to 10 MHz. The crystal is connected to the SOCI and SOSCO pins.
- High-Speed Crystal (HS): Crystals in the range of 10 to 40 MHz. The crystal is connected to the SOSCI and SOSCO pins.
- External Clock (EC): External clock signal up to 64 MHz. The external clock signal is directly applied to SOSCI pin.

9.3 Oscillator Control Registers

REGISTER 9-1: OSCCON: OSCILLATOR CONTROL REGISTER(1,3)

U-0	R-0	R-0	R-0	U-0	R/W-y	R/W-y	R/W-y
—	COSC<2:0>			—	NOSC<2:0>(2)		
bit 15							bit 8

R/W-0	R/W-0	R-0	U-0	R/C-0	U-0	R/W-0	R/W-0
CLKLOCK	IOLOCK	LOCK	—	CF	—	LPOSCEN	OSWEN
bit 7							bit 0

Legend:	y = Value set from Configuration bits on POR		C = Clear only bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **COSC<2:0>:** Current Oscillator Selection bits (read-only)
111 = Fast RC oscillator (FRC) with Divide-by-n
110 = Fast RC oscillator (FRC) with Divide-by-16
101 = Low-Power RC oscillator (LPRC)
100 = Secondary oscillator (SOSC)
011 = Primary oscillator (XT, HS, EC) with PLL
010 = Primary oscillator (XT, HS, EC)
001 = Fast RC Oscillator (FRC) with divide-by-N and PLL (FRCDIVN + PLL)
000 = Fast RC oscillator (FRC)

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **NOSC<2:0>:** New Oscillator Selection bits(2)
111 = Fast RC oscillator (FRC) with Divide-by-n
110 = Fast RC oscillator (FRC) with Divide-by-16
101 = Low-Power RC oscillator (LPRC)
100 = Secondary oscillator (SOSC)
011 = Primary oscillator (XT, HS, EC) with PLL
010 = Primary oscillator (XT, HS, EC)
001 = Fast RC Oscillator (FRC) with divide-by-N and PLL (FRCDIVN + PLL)
000 = Fast RC oscillator (FRC)

bit 7 **CLKLOCK:** Clock Lock Enable bit
If clock switching is enabled and FSCM is disabled, FCKSM<1:0>(FOSC<7:6>) = 0b01
1 = Clock switching is disabled, system clock source is locked
0 = Clock switching is enabled, system clock source can be modified by clock switching

bit 6 **IOLOCK:** Peripheral Pin Select Lock bit
1 = Peripherial pin select is locked, write to peripheral pin select registers not allowed
0 = Peripherial pin select is not locked, write to peripheral pin select registers allowed

bit 5 **LOCK:** PLL Lock Status bit (read-only)
1 = Indicates that PLL is in lock, or PLL start-up timer is satisfied
0 = Indicates that PLL is out of lock, start-up timer is in progress or PLL is disabled

bit 4 **Unimplemented:** Read as '0'

Note 1: Writes to this register require an unlock sequence. Refer to **Section 39. "Oscillator (Part III)"** (DS70216) in the *"dsPIC33F/PIC24H Family Reference Manual"* (available from the Microchip website) for details.

2: Direct clock switches between any primary oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transition clock source between the two PLL modes.

3: This register is reset only on a Power-on Reset (POR).

10.2.2 IDLE MODE

The following occur in Idle mode:

- The CPU stops executing instructions.
- The WDT is automatically cleared.
- The system clock source remains active. By default, all peripheral modules continue to operate normally from the system clock source, but can also be selectively disabled (see **Section 10.4 "Peripheral Module Disable"**).
- If the WDT or FSCM is enabled, the LPRC also remains active.

The device wakes from Idle mode on any of these events:

- Any interrupt that is individually enabled
- Any form of device Reset
- A WDT time-out

On wake-up from Idle mode, the clock is reapplied to the CPU and instruction execution will begin (2-4 clock cycles later), starting with the instruction following the `PWRSAV` instruction, or the first instruction in the ISR.

10.2.3 INTERRUPTS COINCIDENT WITH POWER SAVE INSTRUCTIONS

Any interrupt that coincides with the execution of a `PWRSAV` instruction is held off until entry into Sleep or Idle mode has completed. The device then wakes up from Sleep or Idle mode.

10.3 Doze Mode

The preferred strategies for reducing power consumption are changing clock speed and invoking one of the power-saving modes. In some circumstances, this cannot be practical. For example, it may be necessary for an application to maintain uninterrupted synchronous communication, even while it is doing nothing else. Reducing system clock speed can introduce communication errors, while using a power-saving mode can stop communications completely.

Doze mode is a simple and effective alternative method to reduce power consumption while the device is still executing code. In this mode, the system clock continues to operate from the same source and at the same speed. Peripheral modules continue to be clocked at the same speed, while the CPU clock speed is reduced. Synchronization between the two clock domains is maintained, allowing the peripherals to access the SFRs while the CPU executes code at a slower rate.

Doze mode is enabled by setting the DOZEN bit (CLKDIV<11>). The ratio between peripheral and core clock speed is determined by the DOZE<2:0> bits (CLKDIV<14:12>). There are eight possible configurations, from 1:1 to 1:128, with 1:1 being the default setting.

Programs can use Doze mode to selectively reduce power consumption in event-driven applications. This allows clock-sensitive functions, such as synchronous communications, to continue without interruption while the CPU idles, waiting for something to invoke an interrupt routine. An automatic return to full-speed CPU operation on interrupts can be enabled by setting the ROI bit (CLKDIV<15>). By default, interrupt events have no effect on Doze mode operation.

For example, suppose the device is operating at 20 MIPS and the ECAN module has been configured for 500 kbps based on this device operating speed. If the device is placed in Doze mode with a clock frequency ratio of 1:4, the ECAN module continues to communicate at the required bit rate of 500 kbps, but the CPU now starts executing instructions at a frequency of 5 MIPS.

10.4 Peripheral Module Disable

The Peripheral Module Disable (PMD) registers provide a method to disable a peripheral module by stopping all clock sources supplied to that module. When a peripheral is disabled using the appropriate PMD control bit, the peripheral is in a minimum power consumption state. The control and status registers associated with the peripheral are also disabled, so writes to those registers do not have effect and read values are invalid.

A peripheral module is enabled only if both the associated bit in the PMD register is cleared and the peripheral is supported by the specific dsPIC® DSC variant. If the peripheral is present in the device, it is enabled in the PMD register by default.

Note:	If a PMD bit is set, the corresponding module is disabled after a delay of one instruction cycle. Similarly, if a PMD bit is cleared, the corresponding module is enabled after a delay of one instruction cycle (assuming the module control registers are already configured to enable module operation).

REGISTER 11-17: RPOR0: PERIPHERAL PIN SELECT OUTPUT REGISTER 0

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	RP1R<4:0>				
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	RP0R<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **RP1R<4:0>:** Peripheral Output Function is Assigned to RP1 Output Pin bits (see Table 11-2 for peripheral function numbers)

bit 7-5 **Unimplemented:** Read as '0'

bit 4-0 **RP0R<4:0>:** Peripheral Output Function is Assigned to RP0 Output Pin bits (see Table 11-2 for peripheral function numbers)

REGISTER 11-18: RPOR1: PERIPHERAL PIN SELECT OUTPUT REGISTER 1

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	RP3R<4:0>				
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	RP2R<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **RP3R<4:0>:** Peripheral Output Function is Assigned to RP3 Output Pin bits (see Table 11-2 for peripheral function numbers)

bit 7-5 **Unimplemented:** Read as '0'

bit 4-0 **RP2R<4:0>:** Peripheral Output Function is Assigned to RP2 Output Pin bits (see Table 11-2 for peripheral function numbers)

NOTES:

REGISTER 17-2: I2CxSTAT: I2Cx STATUS REGISTER (CONTINUED)

bit 3 **S:** Start bit
1 = Indicates that a Start (or Repeated Start) bit has been detected last
0 = Start bit was not detected last
Hardware set or clear when Start, Repeated Start or Stop detected.

bit 2 **R_W:** Read/Write Information bit (when operating as I^2C slave)
1 = Read – indicates data transfer is output from slave
0 = Write – indicates data transfer is input to slave
Hardware set or clear after reception of I^2C device address byte.

bit 1 **RBF:** Receive Buffer Full Status bit
1 = Receive complete, I2CxRCV is full
0 = Receive not complete, I2CxRCV is empty
Hardware set when I2CxRCV is written with received byte. Hardware clear when software reads I2CxRCV.

bit 0 **TBF:** Transmit Buffer Full Status bit
1 = Transmit in progress, I2CxTRN is full
0 = Transmit complete, I2CxTRN is empty
Hardware set when software writes I2CxTRN. Hardware clear at completion of data transmission.

19.3 Modes of Operation

The ECAN module can operate in one of several operation modes selected by the user. These modes include:

- Initialization mode
- Disable mode
- Normal Operation mode
- Listen Only mode
- Listen All Messages mode
- Loopback mode

Modes are requested by setting the REQOP<2:0> bits (CiCTRL1<10:8>). Entry into a mode is Acknowledged by monitoring the OPMODE<2:0> bits (CiCTRL1<7:5>). The module does not change the mode and the OPMODE bits until a change in mode is acceptable, generally during bus Idle time, which is defined as at least 11 consecutive recessive bits.

19.3.1 INITIALIZATION MODE

In the Initialization mode, the module does not transmit or receive. The error counters are cleared and the interrupt flags remain unchanged. The user application has access to Configuration registers that are access restricted in other modes. The module protects the user from accidentally violating the CAN protocol through programming errors. All registers which control the configuration of the module cannot be modified while the module is on-line. The ECAN module is not allowed to enter the Configuration mode while a transmission is taking place. The Configuration mode serves as a lock to protect the following registers:

- All Module Control registers
- Baud Rate and Interrupt Configuration registers
- Bus Timing registers
- Identifier Acceptance Filter registers
- Identifier Acceptance Mask registers

19.3.2 DISABLE MODE

In Disable mode, the module does not transmit or receive. The module has the ability to set the WAKIF bit due to bus activity, however, any pending interrupts remains and the error counters retains their value.

If the REQOP<2:0> bits (CiCTRL1<10:8>) = 001, the module enters the Module Disable mode. If the module is active, the module waits for 11 recessive bits on the CAN bus, detect that condition as an Idle bus, then accept the module disable command. When the OPMODE<2:0> bits (CiCTRL1<7:5>) = 001, that indicates whether the module successfully went into Module Disable mode. The I/O pins reverts to normal I/O function when the module is in the Module Disable mode.

The module can be programmed to apply a low-pass filter function to the CiRX input line while the module or the CPU is in Sleep mode. The WAKFIL bit (CiCFG2<14>) enables or disables the filter.

Note:	Typically, if the ECAN module is allowed to transmit in a particular mode of operation and a transmission is requested immediately after the ECAN module has been placed in that mode of operation, the module waits for 11 consecutive recessive bits on the bus before starting transmission. If the user switches to Disable mode within this 11-bit period, then this transmission is aborted and the corresponding TXABT bit is set and TXREQ bit is cleared.

19.3.3 NORMAL OPERATION MODE

Normal Operation mode is selected when REQOP<2:0> = 000. In this mode, the module is activated and the I/O pins assumes the CAN bus functions. The module transmits and receive CAN bus messages via the CiTX and CiRX pins.

19.3.4 LISTEN ONLY MODE

If the Listen Only mode is activated, the module on the CAN bus is passive. The transmitter buffers revert to the port I/O function. The receive pins remain inputs. For the receiver, no error flags or Acknowledge signals are sent. The error counters are deactivated in this state. The Listen Only mode can be used for detecting the baud rate on the CAN bus. To use this, it is necessary that there are at least two further nodes that communicate with each other.

19.3.5 LISTEN ALL MESSAGES MODE

The module can be set to ignore all errors and receive any message. The Listen All Messages mode is activated by setting REQOP<2:0> = '111'. In this mode, the data which is in the message assembly buffer, until the time an error occurred, is copied in the receive buffer and can be read via the CPU interface.

19.3.6 LOOPBACK MODE

If the Loopback mode is activated, the module connects the internal transmit signal to the internal receive signal at the module boundary. The transmit and receive pins revert to their port I/O function.

19.4 ECAN Resources

Many useful resources related to ECAN are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en532311

19.4.1 KEY RESOURCES

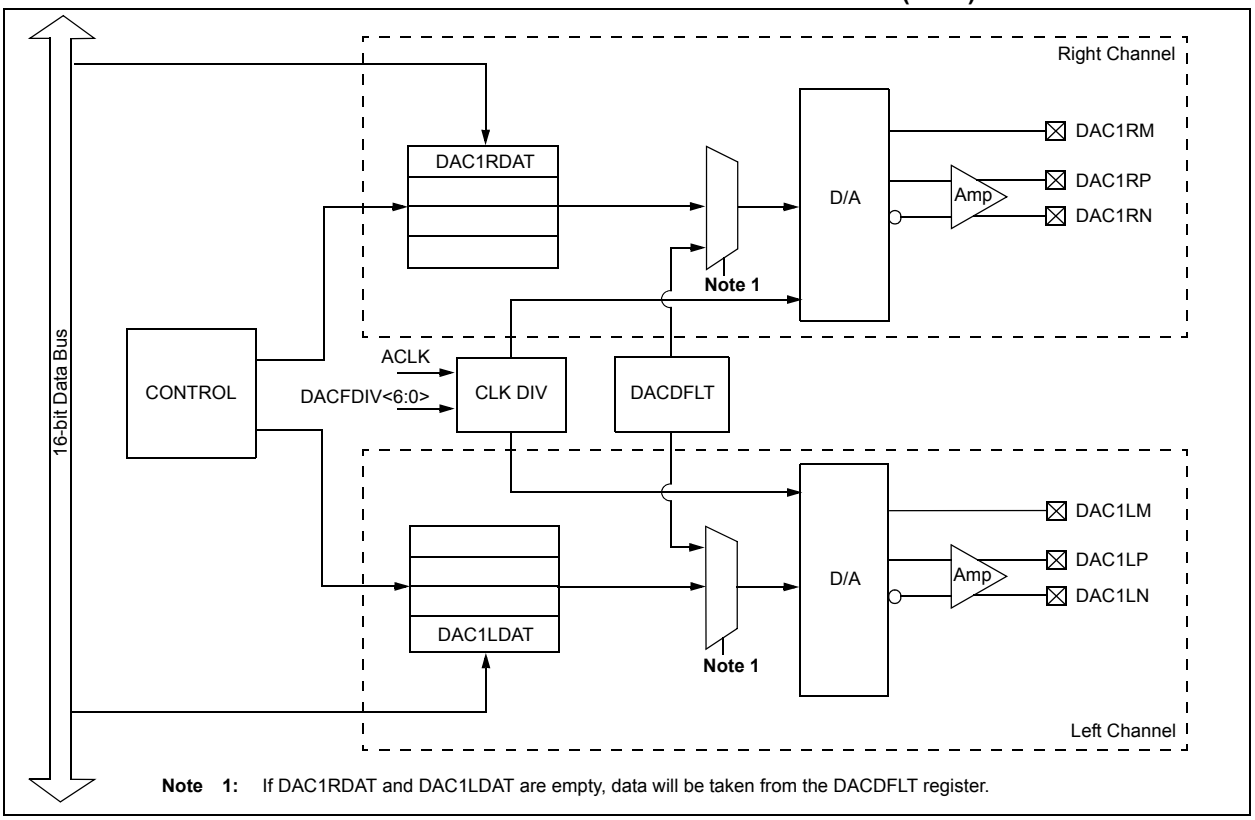
- **Section 21. "Enhanced Controller Area Network (ECAN™)"** (DS70185)
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related dsPIC33F/PIC24H Family Reference Manuals Sections
- Development Tools

22.4 DAC Clock

The DAC clock signal clocks the internal logic of the Audio DAC module. The data sample rate of the Audio DAC is an integer division of the rate of the DAC clock. The DAC clock is generated via a clock divider circuit that accepts an auxiliary clock from the auxiliary oscillator.

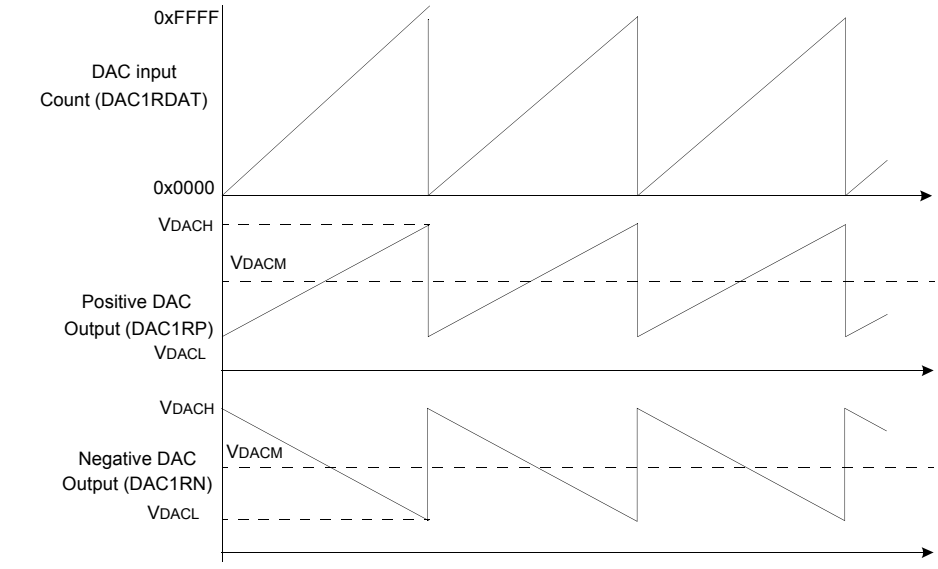
The divisor ratio is programmed by clock divider bits (DACFDIV<6:0>) in the DAC Control register (DAC1CON). The resulting DAC clock must not exceed 25.6 MHz. If lower sample rates are to be used, then the DAC filter clock frequency may be reduced to reduce power consumption. The DAC clock frequency is 256 times the sampling frequency.

FIGURE 22-1: BLOCK DIAGRAM OF AUDIO DIGITAL-TO-ANALOG (DAC) CONVERTER



Note 1: If DAC1RDAT and DAC1LDAT are empty, data will be taken from the DACDFLT register.

FIGURE 22-2: AUDIO DAC OUTPUT FOR RAMP INPUT (UNSIGNED)



Note: $V_{OD+} = V_{DACH} - V_{DACL}$, $V_{OD-} = V_{DACL} - V_{DACH}$; refer to Audio DAC Module Specifications, Table 30-46, for typical values.

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles	Status Flags Affected
10	BTSC	BTSC f,#bit4	Bit Test f, Skip if Clear	1	1 (2 or 3)	None
		BTSC Ws,#bit4	Bit Test Ws, Skip if Clear	1	1 (2 or 3)	None
11	BTSS	BTSS f,#bit4	Bit Test f, Skip if Set	1	1 (2 or 3)	None
		BTSS Ws,#bit4	Bit Test Ws, Skip if Set	1	1 (2 or 3)	None
12	BTST	BTST f,#bit4	Bit Test f	1	1	Z
		BTST.C Ws,#bit4	Bit Test Ws to C	1	1	C
		BTST.Z Ws,#bit4	Bit Test Ws to Z	1	1	Z
		BTST.C Ws,Wb	Bit Test Ws<Wb> to C	1	1	C
		BTST.Z Ws,Wb	Bit Test Ws<Wb> to Z	1	1	Z
13	BTSTS	BTSTS f,#bit4	Bit Test then Set f	1	1	Z
		BTSTS.C Ws,#bit4	Bit Test Ws to C, then Set	1	1	C
		BTSTS.Z Ws,#bit4	Bit Test Ws to Z, then Set	1	1	Z
14	CALL	CALL lit23	Call subroutine	2	2	None
		CALL Wn	Call indirect subroutine	1	2	None
15	CLR	CLR f	f = 0x0000	1	1	None
		CLR WREG	WREG = 0x0000	1	1	None
		CLR Ws	Ws = 0x0000	1	1	None
		CLR Acc,Wx,Wxd,Wy,Wyd,AWB	Clear Accumulator	1	1	OA,OB,SA,SB
16	CLRWDT	CLRWDT	Clear Watchdog Timer	1	1	WDTO,Sleep
17	COM	COM f	$f = \overline{f}$	1	1	N,Z
		COM f,WREG	$WREG = \overline{f}$	1	1	N,Z
		COM Ws,Wd	$Wd = \overline{Ws}$	1	1	N,Z
18	CP	CP f	Compare f with WREG	1	1	C,DC,N,OV,Z
		CP Wb,#lit5	Compare Wb with lit5	1	1	C,DC,N,OV,Z
		CP Wb,Ws	Compare Wb with Ws (Wb – Ws)	1	1	C,DC,N,OV,Z
19	CP0	CP0 f	Compare f with 0x0000	1	1	C,DC,N,OV,Z
		CP0 Ws	Compare Ws with 0x0000	1	1	C,DC,N,OV,Z
20	CPB	CPB f	Compare f with WREG, with Borrow	1	1	C,DC,N,OV,Z
		CPB Wb,#lit5	Compare Wb with lit5, with Borrow	1	1	C,DC,N,OV,Z
		CPB Wb,Ws	Compare Wb with Ws, with Borrow ($Wb – Ws – \overline{C}$)	1	1	C,DC,N,OV,Z
21	CPSEQ	CPSEQ Wb, Wn	Compare Wb with Wn, skip if =	1	1 (2 or 3)	None
22	CPSGT	CPSGT Wb, Wn	Compare Wb with Wn, skip if >	1	1 (2 or 3)	None
23	CPSLT	CPSLT Wb, Wn	Compare Wb with Wn, skip if <	1	1 (2 or 3)	None
24	CPSNE	CPSNE Wb, Wn	Compare Wb with Wn, skip if ≠	1	1 (2 or 3)	None
25	DAW	DAW Wn	Wn = decimal adjust Wn	1	1	C
26	DEC	DEC f	f = f – 1	1	1	C,DC,N,OV,Z
		DEC f,WREG	WREG = f – 1	1	1	C,DC,N,OV,Z
		DEC Ws,Wd	Wd = Ws – 1	1	1	C,DC,N,OV,Z
27	DEC2	DEC2 f	f = f – 2	1	1	C,DC,N,OV,Z
		DEC2 f,WREG	WREG = f – 2	1	1	C,DC,N,OV,Z
		DEC2 Ws,Wd	Wd = Ws – 2	1	1	C,DC,N,OV,Z
28	DISI	DISI #lit14	Disable Interrupts for k instruction cycles	1	1	None

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles	Status Flags Affected
66	RRNC	RRNC	f	f = Rotate Right (No Carry) f	1	1	N,Z
		RRNC	f,WREG	WREG = Rotate Right (No Carry) f	1	1	N,Z
		RRNC	Ws,Wd	Wd = Rotate Right (No Carry) Ws	1	1	N,Z
67	SAC	SAC	Acc,#Slit4,Wdo	Store Accumulator	1	1	None
		SAC.R	Acc,#Slit4,Wdo	Store Rounded Accumulator	1	1	None
68	SE	SE	Ws,Wnd	Wnd = sign-extended Ws	1	1	C,N,Z
69	SETM	SETM	f	f = 0xFFFF	1	1	None
		SETM	WREG	WREG = 0xFFFF	1	1	None
		SETM	Ws	Ws = 0xFFFF	1	1	None
70	SFTAC	SFTAC	Acc,Wn	Arithmetic Shift Accumulator by (Wn)	1	1	OA,OB,OAB, SA,SB,SAB
		SFTAC	Acc,#Slit6	Arithmetic Shift Accumulator by Slit6	1	1	OA,OB,OAB, SA,SB,SAB
71	SL	SL	f	f = Left Shift f	1	1	C,N,OV,Z
		SL	f,WREG	WREG = Left Shift f	1	1	C,N,OV,Z
		SL	Ws,Wd	Wd = Left Shift Ws	1	1	C,N,OV,Z
		SL	Wb,Wns,Wnd	Wnd = Left Shift Wb by Wns	1	1	N,Z
		SL	Wb,#lit5,Wnd	Wnd = Left Shift Wb by lit5	1	1	N,Z
72	SUB	SUB	Acc	Subtract Accumulators	1	1	OA,OB,OAB, SA,SB,SAB
		SUB	f	f = f – WREG	1	1	C,DC,N,OV,Z
		SUB	f,WREG	WREG = f – WREG	1	1	C,DC,N,OV,Z
		SUB	#lit10,Wn	Wn = Wn – lit10	1	1	C,DC,N,OV,Z
		SUB	Wb,Ws,Wd	Wd = Wb – Ws	1	1	C,DC,N,OV,Z
		SUB	Wb,#lit5,Wd	Wd = Wb – lit5	1	1	C,DC,N,OV,Z
73	SUBB	SUBB	f	f = f – WREG – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBB	f,WREG	WREG = f – WREG – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBB	#lit10,Wn	Wn = Wn – lit10 – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBB	Wb,Ws,Wd	Wd = Wb – Ws – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBB	Wb,#lit5,Wd	Wd = Wb – lit5 – ($\overline{C}$)	1	1	C,DC,N,OV,Z
74	SUBR	SUBR	f	f = WREG – f	1	1	C,DC,N,OV,Z
		SUBR	f,WREG	WREG = WREG – f	1	1	C,DC,N,OV,Z
		SUBR	Wb,Ws,Wd	Wd = Ws – Wb	1	1	C,DC,N,OV,Z
		SUBR	Wb,#lit5,Wd	Wd = lit5 – Wb	1	1	C,DC,N,OV,Z
75	SUBBR	SUBBR	f	f = WREG – f – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBBR	f,WREG	WREG = WREG – f – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBBR	Wb,Ws,Wd	Wd = Ws – Wb – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBBR	Wb,#lit5,Wd	Wd = lit5 – Wb – ($\overline{C}$)	1	1	C,DC,N,OV,Z
76	SWAP	SWAP.b	Wn	Wn = nibble swap Wn	1	1	None
		SWAP	Wn	Wn = byte swap Wn	1	1	None
77	TBLRDH	TBLRDH	Ws,Wd	Read Prog<23:16> to Wd<7:0>	1	2	None
78	TBLRDL	TBLRDL	Ws,Wd	Read Prog<15:0> to Wd	1	2	None
79	TBLWTH	TBLWTH	Ws,Wd	Write Ws<7:0> to Prog<23:16>	1	2	None
80	TBLWTL	TBLWTL	Ws,Wd	Write Ws to Prog<15:0>	1	2	None
81	ULNK	ULNK		Unlink Frame Pointer	1	1	None
82	XOR	XOR	f	f = f .XOR. WREG	1	1	N,Z
		XOR	f,WREG	WREG = f .XOR. WREG	1	1	N,Z
		XOR	#lit10,Wn	Wd = lit10 .XOR. Wd	1	1	N,Z
		XOR	Wb,Ws,Wd	Wd = Wb .XOR. Ws	1	1	N,Z
		XOR	Wb,#lit5,Wd	Wd = Wb .XOR. lit5	1	1	N,Z
83	ZE	ZE	Ws,Wnd	Wnd = Zero-extend Ws	1	1	C,Z,N

TABLE 30-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.(3)	**Typical(2)**	**Max**	**Units**	**Conditions**		
Power-Down Current (I_{PD})(1)						
DC60d	24	68	µA	-40°C	3.3V	Base Power-Down Current(3,4)
DC60a	28	87	µA	+25°C		
DC60b	124	292	µA	+85°C		
DC60c	350	1000	µA	+125°C		
DC61d	8	13	µA	-40°C	3.3V	Watchdog Timer Current: ΔI_{WDT}(3,5)
DC61a	10	15	µA	+25°C		
DC61b	12	20	µA	+85°C		
DC61c	13	25	µA	+125°C		

Note 1: I_{PD} (Sleep) current is measured as follows:

- CPU core is off (i.e., Sleep mode), oscillator is configured in EC mode and external clock active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration word
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR}$ = V_{DD}, WDT and FSCM are disabled, all peripheral modules are disabled (PMDx bits are all '1's)
- RTCC is disabled
- JTAG is disabled

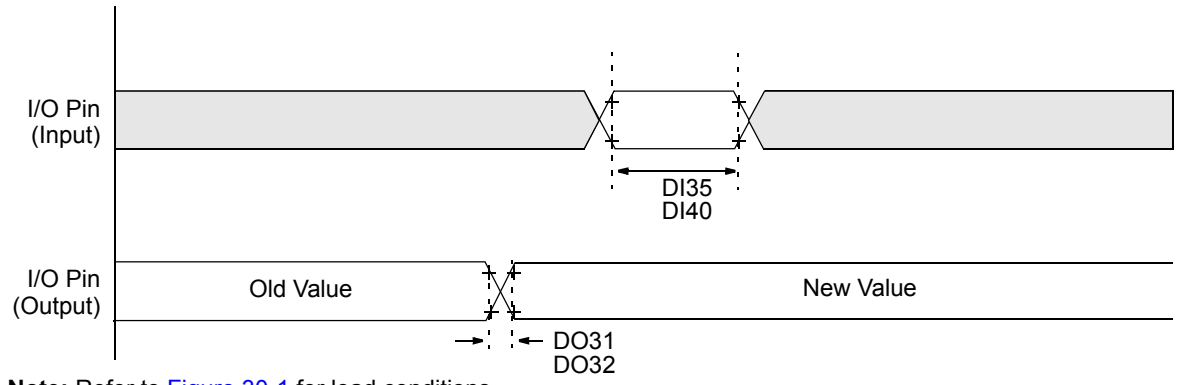
2: Data in the "Typ" column is at 3.3V, +25ºC unless otherwise stated.

3: The Watchdog Timer Current is the additional current consumed when the WDT module is enabled. This current should be added to the base I_{PD} current.

4: These currents are measured on the device containing the most memory in this family.

5: These parameters are characterized, but are not tested in manufacturing.

FIGURE 30-3: CLKO AND I/O TIMING CHARACTERISTICS



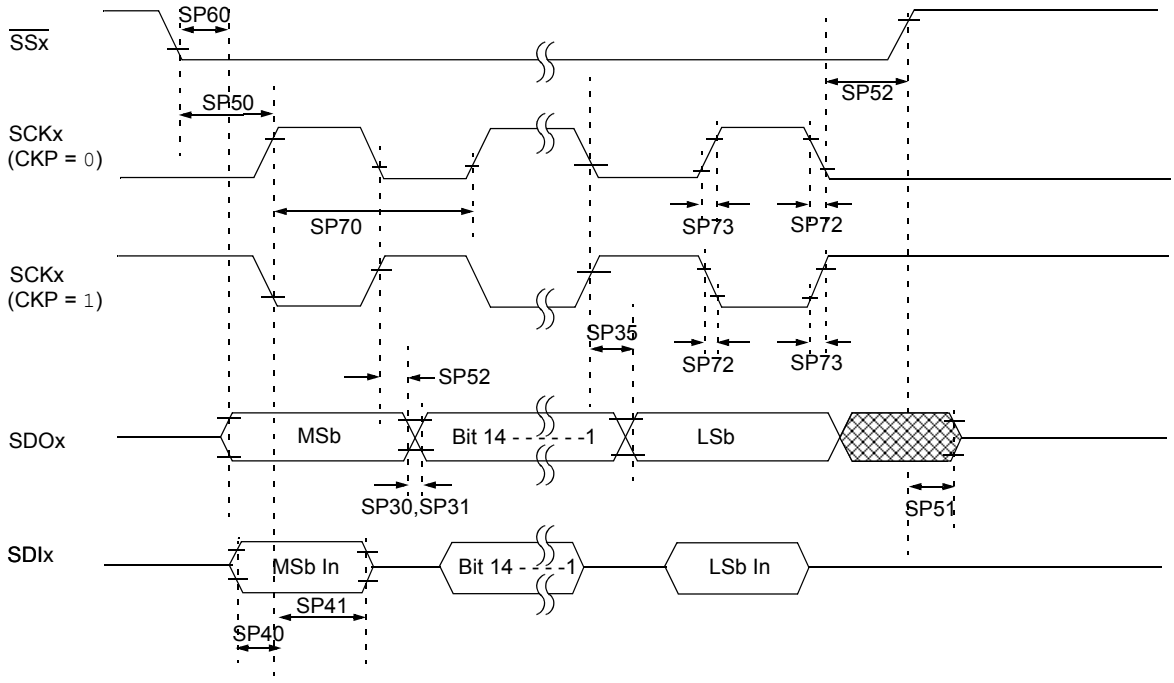
Note: Refer to Figure 30-1 for load conditions.

TABLE 30-20: I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
DO31	TIOR	Port Output Rise Time	—	10	25	ns	—
DO32	TIOF	Port Output Fall Time	—	10	25	ns	—
DI35	TINP	INTx Pin High or Low Time (input)	20	—	—	ns	—
DI40	TRBP	CNx High or Low Time (input)	2	—	—	TCY	—

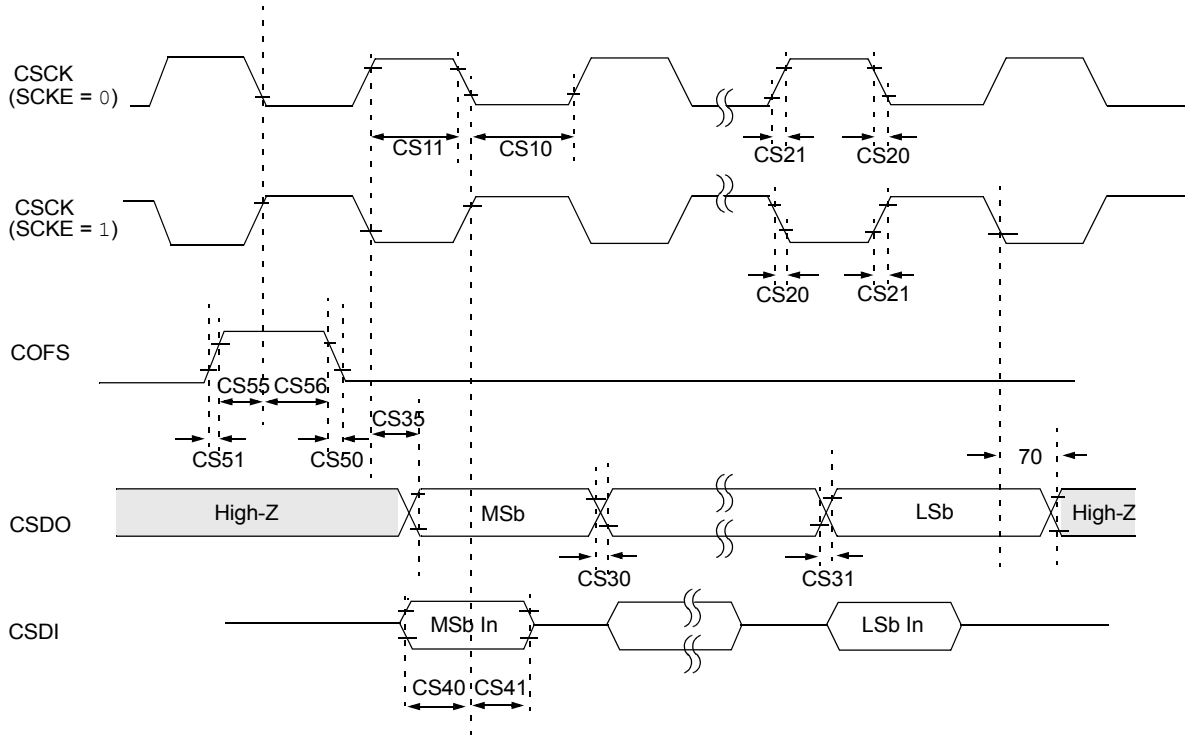
Note 1: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated.

FIGURE 30-14: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

FIGURE 30-21: DCI MODULE (MULTI-CHANNEL, I^2S MODES) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

31.2 AC Characteristics and Timing Parameters

The information contained in this section defines dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 AC characteristics and timing parameters for high temperature devices. However, all AC timing specifications in this section are the same as those in **Section 30.2 "AC Characteristics and Timing Parameters"**, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, parameter OS53 in **Section 30.2 "AC Characteristics and Timing Parameters"** is the Industrial and Extended temperature equivalent of HOS53.

TABLE 31-8: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤TA ≤+150°C for High Temperature Operating voltage VDD range as described in Table 31-1.

FIGURE 31-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

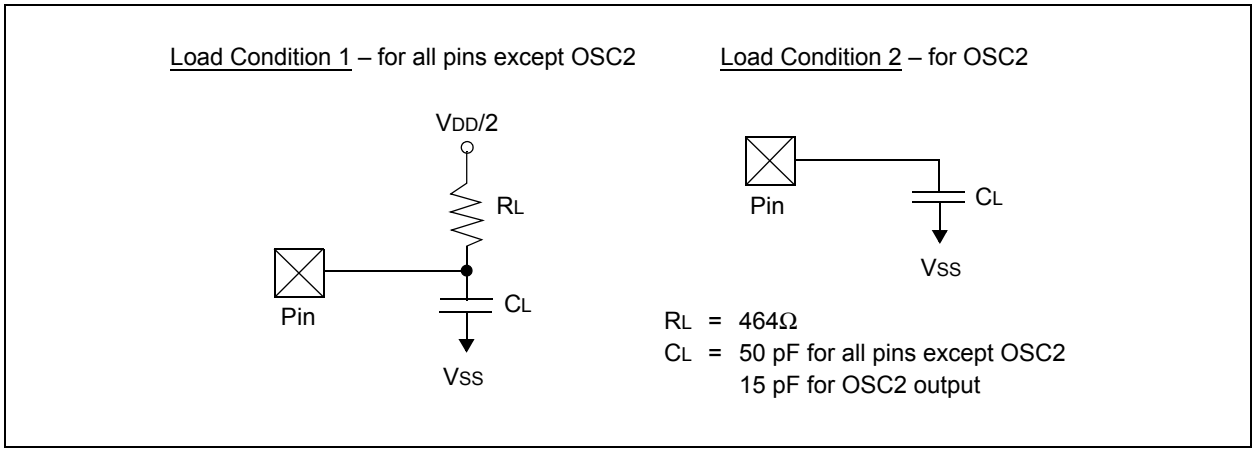


TABLE 31-9: PLL CLOCK TIMING SPECIFICATIONS

AC CHARACTERISTICS		**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤TA ≤+150°C for High Temperature					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
HOS53	DCLK	CLKO Stability (Jitter)(1)	-5	0.5	5	%	Measured over 100 ms period

Note 1: These parameters are characterized, but are not tested in manufacturing.